CLAIMS

[1] A cover tape comprising at least a base layer (A), an intermediate layer (B), a peeling layer (C) which comprises a thermoplastic resin as a main component, and a heat seal layer (D) which comprises a thermoplastic resin as a main component heat-sealable to a carrier tape, wherein

the thermoplastic resin forming the peeling layer (C) has a tensile storage modulus (c) of at least 1×10^6 Pa and at most 1×10^8 Pa at 23 °C;

the thermoplastic resin forming the heat seal layer (D) has a tensile storage modulus (d) of at least 1×10^8 Pa and at most 1×10^{10} Pa at 23 °C; and

a ratio between (c) and (d) is $1 \times 10^4 \geq (d)/(c) \geq 1 \times 10$.

[2] The cover tape according to claim 1, wherein the thermoplastic resin constituting the peeling layer (C) comprises any one of, or a combination of two or more of, an acrylic resin, a polyester resin, an ethylene-vinyl acetate copolymer resin, an ethylene-acrylic acid copolymer resin, an ethylene-methacrylic acid copolymer resin, a styrene-butadiene copolymer resin and a hydrogenated resin thereof, and a styrene-isoprene copolymer resin and a hydrogenated resin thereof.

[3] The cover tape according to claim 1, wherein the thermoplastic resin constituting the heat seal layer (D) comprises any one of, or a combination of two or more of, an acrylic resin, an ester resin and a styrene resin.

[4] The cover tape according to claim 1, wherein the resin constituting the intermediate layer (B) comprises a metallocene linear low density polyethylene resin.

[5] The cover tape according to claim 1, wherein 2 to 15 parts by mass of a carbon nanomaterial is added to at least one of the peeling layer (C) and heat seal layer (D) with respect to 100 parts by mass of the thermoplastic resin constituting the layer.

CLAIMS

[1] A cover tape comprising at least a base layer (A), an intermediate layer (B), a peeling layer (C) which comprises a thermoplastic resin as a main component, and a heat seal layer (D) which comprises a thermoplastic resin as a main component heat-sealable to a carrier tape, wherein

the thermoplastic resin forming the peeling layer (C) has a tensile storage modulus (c) of at least 1×10^6 Pa and at most 1×10^8 Pa at 23 °C;

the thermoplastic resin forming the heat seal layer (D) has a tensile storage modulus (d) of at least 1×10^8 Pa and at most 1×10^{10} Pa at 23 °C; and

a ratio between (c) and (d) is $1 \times 10^4 \geq (d)/(c) \geq 1 \times 10$.

[2] The cover tape according to claim 1, wherein the thermoplastic resin constituting the peeling layer (C) comprises any one of, or a combination of two or more of, an acrylic resin, a polyester resin, an ethylene-vinyl acetate copolymer resin, an ethylene-acrylic acid copolymer resin, an ethylene-methacrylic acid copolymer resin, a styrene-butadiene copolymer resin and a hydrogenated resin thereof, and a styrene-isoprene copolymer resin and a hydrogenated resin thereof.

[3] The cover tape according to claim 1, wherein the thermoplastic resin constituting the heat seal layer (D) comprises any one of, or a combination of two or more of, an acrylic resin, an ester resin and a styrene resin.

[4] The cover tape according to claim 1, wherein the resin constituting the intermediate layer (B) comprises a metallocene linear low density polyethylene resin.

[5] The cover tape according to claim 1, wherein 2 to 15 parts by mass of a carbon nanomaterial is added to at least one of the peeling layer (C) and heat seal layer (D) with respect to 100 parts by mass of the thermoplastic resin constituting the layer.